

AMENDMENT TRANSMITTAL LETTER (Large Entity)

Applicant(s): John Rosato et al

Docket No.

SCP 6630

Serial No.
09/408,279Filing Date
29 September 1999Examiner
KornakovGroup Art Unit
1746Invention: **PROCESS AND SYSTEM FOR RINSING OF SEMICONDUCTOR SUBSTRATES**

JAN 14 2002

TO THE ASSISTANT COMMISSIONER FOR PATENTS:

Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated and is transmitted as shown below.

CLAIMS AS AMENDED

	CLAIMS REMAINING AFTER AMENDMENT	HIGHEST # PREV. PAID FOR	NUMBER EXTRA CLAIMS PRESENT	RATE	ADDITIONAL FEE
TOTAL CLAIMS	32 -	79 =	0 x	\$18.00	\$0.00
INDEP. CLAIMS	5 -	9 =	0 x	\$84.00	\$0.00
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					\$0.00
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT					\$0.00

- ☒ No additional fee is required for amendment.
- ☐ Please charge Deposit Account No. _____ in the amount of _____
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Signature

Dated: 23 October 2001

Kathleen A. Frost
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE



In re application of: Rosato et al	Group No.: 1746
Application No.: 09/408,279	Examiner: Kornakov
Filed: September 29, 1999	RESPONSE TO RESTRICTION REQUIREMENT
For: PROCESS AND SYSTEM FOR RINSING OF SEMICONDUCTOR SUBSTRATES	MAILED APRIL 23, 2001

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Washington, DC 20231

Sir:

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I hereby certify that this correspondence is being deposited
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STALLMAN & POLLOCK LLP
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Name

Applicants make the following amendments and remarks in response to the official action
mailed April 23, 2001.

In the Claims

Please cancel Claims 1 - 79 without prejudice, and add new claims 80 - 111.

80. (NEW) A method for rinsing metallized semiconductor substrates with an aqueous medium comprising including in said aqueous medium an amount effective to minimize metal corrosion of an anti-corrosive agent including an organic compound.

81. (NEW) The method of claim 80 wherein the organic compound includes an organic acid.

82. (NEW) A method according to claim 80 in which the organic acid includes an organic carboxylic acid.

Sub
B1

91

112/11C
subp
indef 112/12
original step

cancel

112/2